

Necmettin MaraÅlÄ±

List of Publications by Year in descending order

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128
docs citations

128
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900
citing authors

#	ARTICLE	IF	CITATIONS
1	Solid-liquid surface energies in the Al—CuAl ₂ , Al—NiAl ₃ and Al—Ti systems. <i>Acta Materialia</i> , 1996, 44, 1085-1096.	7.9	158
2	Solid-liquid surface energy of pivalic acid. <i>Journal of Crystal Growth</i> , 1998, 194, 119-124.	1.5	77
3	Solid-liquid interfacial energy of the eutectoid β^2 phase in the Al—Zn eutectic system. <i>Materials Science & Engineering A: Structural Materials: Properties, Microstructure and Processing</i> , 2004, 369, 294-301.	5.6	76
4	Measurements of the microhardness, electrical and thermal properties of the Al—Ni eutectic alloy. <i>Materials & Design</i> , 2012, 34, 707-712.	5.1	64
5	Solid-liquid interfacial energy of camphene. <i>Materials Science & Engineering A: Structural Materials: Properties, Microstructure and Processing</i> , 1999, 270, 343-348.	5.6	62
6	Variation of microindentation hardness with solidification and microstructure parameters in the Al based alloys. <i>Applied Surface Science</i> , 2008, 255, 3071-3078.	6.1	62
7	Dependency of the thermal and electrical conductivity on the temperature and composition of Cu in the Al based Al—Cu alloys. <i>Experimental Thermal and Fluid Science</i> , 2010, 34, 1507-1516.	2.7	62
8	Solid-liquid interface energies in the succinonitrile and succinonitrile—carbon tetrabromide eutectic system. <i>Journal of Crystal Growth</i> , 2003, 247, 613-622.	1.5	60
9	Directional solidification of Al—Cu—Ag alloy. <i>Applied Physics A: Materials Science and Processing</i> , 2009, 95, 923-932.	2.3	59
10	Experimental investigation of the effect of solidification processing parameters on the rod spacings in the Sn—1.2wt.% Cu alloy. <i>Journal of Alloys and Compounds</i> , 2009, 486, 199-206.	5.5	44
11	Influence of growth rate on microstructure, microhardness, and electrical resistivity of directionally solidified Al-7 wt% Ni hypo-eutectic alloy. <i>Metals and Materials International</i> , 2013, 19, 39-44.	3.4	44
12	The effects of microstructure and growth rate on microhardness, tensile strength, and electrical resistivity for directionally solidified Al—Ni—Fe alloys. <i>Journal of Alloys and Compounds</i> , 2016, 660, 23-31.	5.5	44
13	The effect of growth rate on microstructure and microindentation hardness in the In—Bi—Sn ternary alloy at low melting point. <i>Journal of Alloys and Compounds</i> , 2009, 470, 150-156.	5.5	43
14	The microstructure parameters and microhardness of directionally solidified Sn—Ag—Cu eutectic alloy. <i>Journal of Alloys and Compounds</i> , 2009, 485, 264-269.	5.5	43
15	Microstructural, mechanical and electrical characterization of directionally solidified Al—Si—Mg eutectic alloy. <i>Journal of Alloys and Compounds</i> , 2015, 618, 197-203.	5.5	39
16	Effect of solidification processing parameters on the cellular spacings in the Al—0.1wt% Ti and Al—0.5wt% Ti alloys. <i>Journal of Alloys and Compounds</i> , 2007, 439, 114-127.	5.5	38
17	Dependency of microindentation hardness on solidification processing parameters and cellular spacing in the directionally solidified Al based alloys. <i>Journal of Alloys and Compounds</i> , 2009, 478, 281-286.	5.5	36
18	Dependency of eutectic spacings and microhardness on the temperature gradient for directionally solidified Sn—Ag—Cu lead-free solder. <i>Materials Chemistry and Physics</i> , 2010, 119, 442-448.	4.0	36

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19	Experimental determination of solid-liquid interfacial energy for solid Cd in Bi-Cd liquid solutions. <i>Journal of Alloys and Compounds</i> , 2004, 385, 207-213.	5.5	35
20	Microstructural characterization of unidirectional solidified eutectic Al-Si-Ni alloy. <i>Materials Characterization</i> , 2011, 62, 844-851.	4.4	35
21	Measurement of solid-liquid interfacial energy for solid d-camphor solution in equilibrium with succinonitrile d-camphor eutectic liquid. <i>Scripta Materialia</i> , 2006, 55, 235-238.	5.2	33
22	Thermal conductivities of solid and liquid phases in Pb-Cd and Sn-Zn binary eutectic alloys. <i>Thermochimica Acta</i> , 2007, 454, 128-134.	2.7	33
23	Determination of mechanical, electrical and thermal properties of the Sn-Bi-Zn ternary alloy. <i>Journal of Non-Crystalline Solids</i> , 2011, 357, 2876-2881.	3.1	33
24	Thermal conductivities of solid and liquid phases for neopentylglycol, aminomethylpropanediol and their binary alloy. <i>Journal of Physics and Chemistry of Solids</i> , 2009, 70, 72-78.	4.0	31
25	Effect of growth rate and composition on the primary spacing, the dendrite tip radius and mushy zone depth in the directionally solidified succinonitrile-carbon alloys. <i>Journal of Crystal Growth</i> , 2003, 255, 190-203.	1.5	30
26	Solid-liquid interfacial energy of the solid Mg ₂ Zn ₁₁ phase in equilibrium with Zn-Mg eutectic liquid. <i>Journal of Physics Condensed Matter</i> , 2007, 19, 176003.	1.8	30
27	Solid-liquid interfacial energy of pyrene. <i>Journal of Applied Physics</i> , 2006, 100, 123505.	2.5	28
28	Measurement of solid-liquid interfacial energy in succinonitrile-pyrene eutectic system. <i>Materials Letters</i> , 2005, 59, 2953-2958.	2.6	27
29	Solid-liquid interfacial energy of aminomethylpropanediol. <i>Journal Physics D: Applied Physics</i> , 2008, 41, 065309.	2.8	27
30	Dependency of the dendritic arm spacings and tip radius on the growth rate and composition in the directionally solidified succinonitrile-carbon tetrabromide alloys. <i>Journal of Crystal Growth</i> , 2005, 276, 583-593.	1.5	26
31	Solid-liquid interfacial energy for solid succinonitrile in equilibrium with succinonitrile dichlorobenzene eutectic liquid. <i>Thermochimica Acta</i> , 2006, 445, 86-91.	2.7	25
32	Solid-liquid interfacial energy of dichlorobenzene. <i>Journal of Physics Condensed Matter</i> , 2007, 19, 116202.	1.8	25
33	Variations of microhardness with solidification parameters and electrical resistivity with temperature for Al-Cu-Ag eutectic alloy. <i>Current Applied Physics</i> , 2012, 12, 7-10.	2.4	25
34	Solid-liquid interfacial energy of neopentylglycol. <i>Journal of Colloid and Interface Science</i> , 2008, 320, 555-562.	9.4	23
35	Investigation of liquid composition effect on Gibbs-Thomson coefficient and solid-liquid interfacial energy in SCN based binary alloys. <i>Materials Characterization</i> , 2008, 59, 998-1006.	4.4	23
36	Measurement of solid-liquid interfacial energy in the pyrene succinonitrile monotectic system. <i>Journal of Physics Condensed Matter</i> , 2006, 18, 8403-8412.	1.8	22

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37	Determination of interfacial energies in the Al–Ag and Sn–Ag alloys by using Bridgman type solidification apparatus. <i>Journal of Alloys and Compounds</i> , 2009, 488, 138-143.	5.5	22
38	Dependence of Electrical Resistivity on Temperature and Sn Content in Pb-Sn Solders. <i>Journal of Electronic Materials</i> , 2011, 40, 195-200.	2.2	22
39	Microstructural, mechanical, and electrical characterization of directionally solidified Al–Cu–Mg eutectic alloy. <i>Physics of Metals and Metallography</i> , 2017, 118, 389-398.	1.0	22
40	Novel experimental technique to observe equilibrated grain boundary groove shapes in opaque alloys. <i>Journal of Alloys and Compounds</i> , 2009, 476, 213-219.	5.5	21
41	Determination of thermo-electrical properties in Sn based alloys. <i>Metals and Materials International</i> , 2010, 16, 507-515.	3.4	21
42	Effect of solidification parameters on the microstructure of Sn-3.7Ag-0.9Zn solder. <i>Materials Characterization</i> , 2010, 61, 1260-1267.	4.4	21
43	Dependency of thermal and electrical conductivity on temperature and composition of Sn in Pb–Sn alloys. <i>Fluid Phase Equilibria</i> , 2010, 295, 60-67.	2.5	21
44	The measurement of thermal conductivity variation with temperature for Sn-20wt.% In based lead-free ternary solders. <i>Thermochimica Acta</i> , 2013, 554, 63-70.	2.7	21
45	Temperature dependency of thermal conductivity of solid phases for fatty acids. <i>Journal of Thermal Analysis and Calorimetry</i> , 2014, 118, 311-321.	3.6	21
46	Interfacial energy of solid In ₂ Bi intermetallic phase in equilibrium with In–Bi eutectic liquid at 722°C equilibrating temperature. <i>Materials Characterization</i> , 2008, 59, 1101-1110.	4.4	20
47	Determination of thermodynamic properties of aluminum based binary and ternary alloys. <i>Journal of Alloys and Compounds</i> , 2015, 649, 453-460.	5.5	20
48	The measurements of electrical and thermal conductivity variations with temperature and phonon component of the thermal conductivity in Sn–Cd–Sb, Sn–In–Cu, Sn–Ag–Bi and Sn–Bi–Zn alloys. <i>International Journal of Thermal Sciences</i> , 2016, 100, 1-9.	4.9	19
49	The effect of different atomic volumes in the three phases during lamellar eutectic growth. A comparison of experiment and theory in the Al–Al ₂ Cu system. <i>Acta Metallurgica Et Materialia</i> , 1995, 43, 2143-2147.	1.8	18
50	Dependency of Microstructural Parameters and Microindentation Hardness on the Temperature Gradient in the In-Bi-Sn Ternary Alloy with a Low Melting Point. <i>Metals and Materials International</i> , 2008, 14, 575-582.	3.4	18
51	Directional solidification of Al–Cu–Si–Mg quaternary eutectic alloy. <i>Journal of Alloys and Compounds</i> , 2017, 721, 764-771.	5.5	18
52	Experimental determination of solid–liquid interfacial energy for succinonitrile solid solution in equilibrium with the succinonitrile–(D) camphor eutectic liquid. <i>Journal of Materials Science</i> , 2006, 41, 7939-7943.	3.7	17
53	Measurements of Microhardness and Thermal and Electrical Properties of the Binary Zn-0.7wt.%Cu Hypoperitectic Alloy. <i>Journal of Electronic Materials</i> , 2010, 39, 303-311.	2.2	17
54	Thermal conductivity and interfacial energy of solid Bi solution in the Bi–Al–Zn eutectic system. <i>Fluid Phase Equilibria</i> , 2010, 293, 32-41.	2.5	17

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55	Experimental determination of thermal conductivity and solid-liquid interfacial energy of solid Ag ₃ Sn intermetallic in the Sn-Ag-In ternary alloy. <i>Intermetallics</i> , 2010, 18, 2250-2258.	3.9	17
56	Influence of Growth Rate on Eutectic Spacing, Microhardness, and Ultimate Tensile Strength in the Directionally Solidified Al-Cu-Ni Eutectic Alloy. <i>Metallurgical and Materials Transactions B: Process Metallurgy and Materials Processing Science</i> , 2018, 49, 3293-3305.	2.1	17
57	Measurement of solid-liquid interfacial energy in the In-Bi eutectic alloy at low melting temperature. <i>Journal of Physics Condensed Matter</i> , 2007, 19, 506102.	1.8	16
58	Directional solidification and physical properties measurements of the zinc-aluminum eutectic alloy. <i>International Journal of Minerals, Metallurgy and Materials</i> , 2011, 18, 659-664.	4.9	16
59	Thermal conductivity and electrical resistivity dependences on growth rate in the directionally solidified Al-Cu-Ni eutectic alloy. <i>Journal of Alloys and Compounds</i> , 2018, 753, 695-702.	5.5	16
60	Thermal conductivity and interfacial energies of solid Sn solution in the Sn-Ag-In ternary alloy. <i>Chemical Physics Letters</i> , 2010, 496, 263-269.	2.6	15
61	Investigation of the effect of solidification processing parameters on the rod spacings and variation of microhardness with the rod spacing in the Sn-Cu hypereutectic alloy. <i>Journal of Materials Science: Materials in Electronics</i> , 2010, 21, 608-618.	2.2	15
62	Investigation of the effect of solidification processing parameters on microhardness and determination of thermo-physical properties in the Zn-Cu peritectic alloy. <i>Journal of Alloys and Compounds</i> , 2010, 491, 143-148.	5.5	15
63	The measurement of thermal conductivity variation with temperature for solid materials. <i>Measurement: Journal of the International Measurement Confederation</i> , 2013, 46, 161-170.	5.0	15
64	Unidirectional solidification of Zn-rich Zn-Cu hypoperitectic alloy. <i>Journal of Materials Research</i> , 2009, 24, 3422-3431.	2.6	14
65	Thermal conductivity and interfacial energies of solid Sn in the Sn-Cu alloy. <i>Chemical Physics Letters</i> , 2010, 484, 219-224.	2.6	14
66	Determination of thermal conductivity and interfacial energy of solid Zn solution in the Zn-Al-Bi eutectic system. <i>Experimental Thermal and Fluid Science</i> , 2011, 35, 395-404.	2.7	14
67	Investigation of microhardness and thermo-electrical properties in the Sn-Cu hypereutectic alloy. <i>Journal of Materials Science: Materials in Electronics</i> , 2010, 21, 468-474.	2.2	13
68	Determination of interfacial energies of solid Sn solution in the In-Bi-Sn ternary alloy. <i>Materials Characterization</i> , 2009, 60, 183-192.	4.4	12
69	The dependence of lamellar spacings and microhardness on the growth rate in the directionally solidified Bi-43 wt.% Sn alloy at a constant temperature gradient. <i>Metals and Materials International</i> , 2009, 15, 741-751.	3.4	12
70	Thermal and electrical conductivity of Sn-Ag-In alloys. <i>Journal of Non-Crystalline Solids</i> , 2010, 356, 1795-1801.	3.1	12
71	Interfacial energies of p-dichlorobenzene-succinonitrile alloy. <i>Thermochimica Acta</i> , 2007, 463, 44-52.	2.7	11
72	Interfacial Energy of Solid Bismuth in Equilibrium with Bi-In Eutectic Liquid at 109.5 °C, Equilibrating Temperature. <i>Metals and Materials International</i> , 2008, 14, 177-187.	3.4	11

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73	Determination of interfacial energies in the aminomethylpropanediol-neopentylglycol organic alloy. <i>Applied Surface Science</i> , 2009, 255, 3594-3599.	6.1	11
74	Thermal Conductivity Variation with Temperature for Lead-Free Ternary Eutectic Solders. <i>Journal of Electronic Materials</i> , 2013, 42, 3573-3581.	2.2	11
75	Unidirectional solidification of aluminium-nickel eutectic alloy. <i>Metallic Materials</i> , 2010, 48, 291-300.	0.3	11
76	Experimental determination of solid-liquid interfacial energies of solid δ (CuZn ₅) in the Zn-Cu alloy. <i>Journal of Alloys and Compounds</i> , 2009, 487, 103-108.	5.5	10
77	Thermal and electrical conductivities of silver-indium-tin alloys. <i>Journal of Physics and Chemistry of Solids</i> , 2012, 73, 902-910.	4.0	10
78	Determination of solid-liquid interfacial energies in the In-Bi-Sn ternary alloy. <i>Journal Physics D: Applied Physics</i> , 2008, 41, 175302.	2.8	9
79	Interfacial energies of solid CuAl ₂ in the CuAl ₂ -Ag ₂ Al pseudo binary alloy. <i>Thin Solid Films</i> , 2010, 518, 4322-4327.	1.8	9
80	Determination of solid-liquid interfacial energy for a solid Sn in equilibrium with a Sn-Ag-Zn eutectic liquid. <i>Current Applied Physics</i> , 2011, 11, 1060-1066.	2.4	9
81	Variations of thermal conductivity with temperature and composition of Zn in the Bi-[x]at.% Zn-2at.% Al alloys. <i>Thermochimica Acta</i> , 2012, 547, 1-5.	2.7	9
82	Effect of solidification parameters on the microstructure of directionally solidified Sn-Bi-Zn lead-free solder. <i>Metals and Materials International</i> , 2012, 18, 349-354.	3.4	9
83	Dependency of thermal conductivity on the temperature and composition of d-camphor in the neopentylglycol-d-camphor alloys. <i>Thermochimica Acta</i> , 2012, 531, 12-20.	2.7	9
84	The influence of the growth rate on the eutectic spacings, undercoolings and microhardness of directional solidified bismuth-lead eutectic alloy. <i>Current Applied Physics</i> , 2013, 13, 587-593.	2.4	9
85	Measurement of Solid-Liquid Interfacial Energy for Solid Zn in Equilibrium with the ZnMg Eutectic Liquid. <i>Metallurgical and Materials Transactions A: Physical Metallurgy and Materials Science</i> , 2007, 38, 1539-1545.	2.2	8
86	Thermal conductivity and interfacial energies of solid Sn ₃ Sb ₂ in the Sn-Sb peritectic system. <i>Thermochimica Acta</i> , 2011, 520, 25-32.	2.7	8
87	Solid-liquid interfacial energy of solid succinonitrile solution in equilibrium with succinonitrile-neopentylglycol eutectic liquid. <i>Journal of Crystal Growth</i> , 2013, 380, 209-217.	1.5	8
88	The use of measured values of surface energies to test heterogeneous nucleation theory. <i>Journal of Crystal Growth</i> , 1998, 191, 558-562.	1.5	7
89	Solid-liquid interfacial energy of neopentylglycol solid solution in equilibrium with neopentylglycol-(D) camphor eutectic liquid. <i>Journal of Crystal Growth</i> , 2012, 338, 181-188.	1.5	7
90	Directional solidification of Zn-Al-Cu eutectic alloy by the vertical Bridgman method. <i>Journal of Mining and Metallurgy, Section B: Metallurgy</i> , 2015, 51, 67-72.	0.8	7

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91	The Measurement of Thermal Conductivity Variation with Temperature for Sn-Based Lead-Free Binary Solders. Metallurgical and Materials Transactions B: Process Metallurgy and Materials Processing Science, 2014, 45, 1739-1749.	2.1	6
92	Directionally Solidified Al-Cu-Si-Fe Quaternary Eutectic Alloys. Physics of Metals and Metallography, 2020, 121, 78-83.	1.0	6
93	Effects of growth rate and temperature gradient on the microstructure parameters in the directionally solidified succinonitrile-7.5wt.% carbon tetrabromide alloy. Journal of Materials Processing Technology, 2008, 202, 145-155.	6.3	5
94	Investigation of directional solidified Al-Ti alloy. Journal of Non-Crystalline Solids, 2009, 355, 1231-1239.	3.1	5
95	The measurement of interfacial energies for solid Sn solution in equilibrium with the Sn-Bi-Ag liquid. Materials Chemistry and Physics, 2013, 139, 153-160.	4.0	5
96	Experimental determination of interfacial energies for solid Sn in equilibrium with Sn-Mg-Zn liquid. Metals and Materials International, 2015, 21, 286-294.	3.4	5
97	Experimental measurements of some thermophysical properties of solid CdSb intermetallic in the Sn-Cd-Sb ternary alloy. Journal of Thermal Analysis and Calorimetry, 2016, 126, 1059-1065.	3.6	5
98	Influences of Directions and Magnitudes of Static Electrical Field on Microstructure and Mechanical Properties for Al-Si Eutectic Alloy. Journal of Materials Engineering and Performance, 2022, 31, 5070-5079.	2.5	5
99	Experimental determination of interfacial energy for solid Zn solution in the Sn-Zn eutectic system. Metals and Materials International, 2012, 18, 95-104.	3.4	4
100	Solid-liquid interfacial energy of solid succinonitrile in equilibrium with succinonitrile-1,4-diiodobenzene eutectic liquid. Journal of Thermal Analysis and Calorimetry, 2015, 119, 1867-1874.	3.6	4
101	Dependence of microstructural, mechanical and electrical properties on growth rates in directional solidified Zn-Al-Bi eutectic alloy. Transactions of Nonferrous Metals Society of China, 2016, 26, 2320-2335.	4.2	4
102	Dependence of microstructure, microhardness, tensile strength and electrical resistivity on growth rates for directionally solidified Zn-Al-Sb eutectic alloy. International Journal of Materials Research, 2016, 107, 1005-1015.	0.3	4
103	The experimental determination of thermophysical properties of intermetallic CuAl 2 phase in equilibrium with (Al + Cu + Si) liquid. Journal of Chemical Thermodynamics, 2016, 97, 228-234.	2.0	4
104	Hardness and electrical resistivity of Al-13 wt % Mg ₂ Si pseudoeutectic alloy. Russian Journal of Non-Ferrous Metals, 2017, 58, 15-21.	0.6	4
105	Effects of Bi content on thermal, microstructure and mechanical properties of Sn-Bi-In-Zn solder alloy systems. Journal of Materials Science: Materials in Electronics, 2022, 33, 11-26.	2.2	4
106	MEASUREMENTS OF SOLID-LIQUID INTERFACIAL ENERGIES IN THE ORGANIC MONOTECTIC ALLOYS. Surface Review and Letters, 2009, 16, 203-214.	1.1	3
107	Interfacial energies of carbon tetrabromide. Current Applied Physics, 2009, 9, 359-366.	2.4	3
108	The Experimental Determination of Interfacial Energies for Solid Cd in Equilibrium with Sn-Cd-Sb Liquid. Metallurgical and Materials Transactions A: Physical Metallurgy and Materials Science, 2014, 45, 1161-1170.	2.2	3

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109	Thermal conductivity and interfacial energy of solid Bi in the Bi–Ag eutectic system. Journal of Thermal Analysis and Calorimetry, 2015, 122, 65-72.	3.6	3
110	Growth of rod structure with static electrical field in the Al–Ni eutectic system. Journal of Materials Science: Materials in Electronics, 2020, 31, 14055-14068.	2.2	3
111	Electro growth of Al Cu eutectic alloy. Materials Characterization, 2020, 161, 110157.	4.4	3
112	Solidification of A356 Alloy Under Different Directions and Magnitudes of Static Electrical Field. International Journal of Metalcasting, 0, , 1.	1.9	3
113	Experimental determination of thermal conductivity and interfacial energies of solid Pb solution in the Pb–Sb eutectic system. Chemical Physics Letters, 2011, 503, 220-225.	2.6	2
114	Solid–liquid interfacial energy of neopentylglycol solid solution in equilibrium with succinonitrile-neopentylglycol-aminomethylpropanediol liquid. Journal of Crystal Growth, 2013, 364, 34-39.	1.5	2
115	Solid–liquid interfacial energy of solid aminomethylpropanediol solution in equilibrium with aminomethylpropanediol–neopentylglycol–D camphor liquid. Thermochimica Acta, 2013, 554, 48-53.	2.7	2
116	Effects of Growth Rate on Eutectic Spacing, Microhardness, and Ultimate Tensile Strength in the Al–Cu–Ti Eutectic Alloy. Physics of Metals and Metallography, 2020, 121, 382-390.	1.0	2
117	Investigations of Electrical Resistivity and Thermal Conductivity Dependences on Growth Rate in the Al–Cu–Ti Eutectic Alloy. International Journal of Thermophysics, 2021, 42, 1.	2.1	2
118	The Experimental Determination of Interfacial Energies for Solid Zn in Equilibrium with Zn-Al-Sb Liquid. Metallurgical and Materials Transactions B: Process Metallurgy and Materials Processing Science, 2015, 46, 2084-2095.	2.1	1
119	Thermophysical properties of NPG solid solution in the NPG–SCN organic system. International Journal of Materials Research, 2018, 109, 219-224.	0.3	1
120	Effect of Sn contents on thermodynamic, microstructure and mechanical properties in the Zn ₉₀ –Bi ₁₀ and Bi ₈₈ –Zn ₁₂ based ternary alloys. Journal of Materials Science: Materials in Electronics, 2019, 30, 3678-3691.	2.2	1
121	The Variations of Electron and Phonon Contributions to the Thermal Conductivity with Temperature in the Sn–Bi–In–Zn Alternative Lead-Free Solder Alloys. Physics of Metals and Metallography, 2020, 121, 1365-1374.	1.0	1
122	BI-IN SÄSTEMÄNDE ELEKTRÅKSEL VE ISIL ÅLETKENLÅK VE ISIL ÅLETKENLÅÅZE FONON KATKISI. Isi Bilimi Ve Teknigi Dergisi/ Journal of Thermal Science and Technology, 2020, 40, 367-378.	0.6	1
123	DETERMINATION OF ANISOTROPY OF CRYSTAL-MELT INTERFACIAL ENERGY FROM THE OBSERVED GRAIN BOUNDARY GROOVE SHAPES AT MULTIPLE ORIENTATIONS. Surface Review and Letters, 2009, 16, 579-588.	1.1	0
124	Solid–Liquid Interfacial Energy of Solid Neopentylglycol Solution in Equilibrium with Neopentylglycol–Aminomethylpropanediol Eutectic Liquid. Metallurgical and Materials Transactions A: Physical Metallurgy and Materials Science, 2013, 44, 4042-4050.	2.2	0
125	Measurements of Thermal Conductivity Variations with Temperature for the Organic Analog of the Nonmetal–Nonmetal System: Urea–4-Bromo-2-Nitroaniline. Metallurgical and Materials Transactions A: Physical Metallurgy and Materials Science, 2013, 44, 4051-4058.	2.2	0
126	Solid–Liquid Interfacial Energy of Solid Succinonitrile in Equilibrium with Succinonitrile–(D)Camphor–Aminomethylpropanediol Eutectic Liquid. International Journal of Thermophysics, 2016, 37, 1.	2.1	0

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127	Thermal Conductivity of Solid Phases for Naphtol, Camphene, Salol, and Bezil. Journal of Thermophysics and Heat Transfer, 2016, 30, 730-736.	1.6	0
128	The variations of electrical resistivity and thermal conductivity with growth rate for the Zn-Al-Cu eutectic alloy. Journal of Materials Science: Materials in Electronics, 2021, 32, 18212-18223.	2.2	0